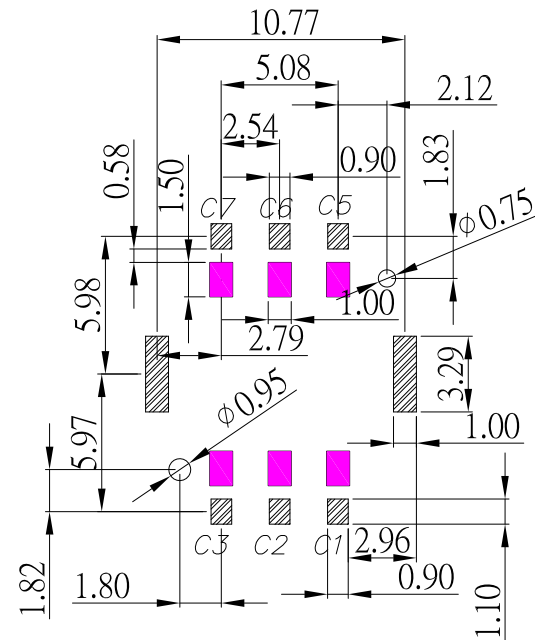
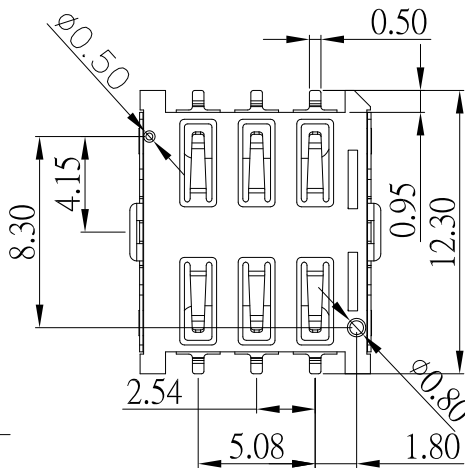
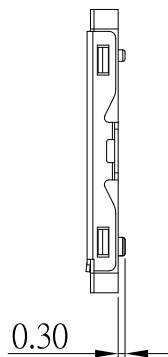
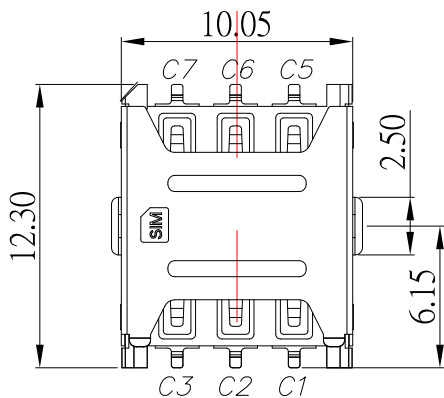
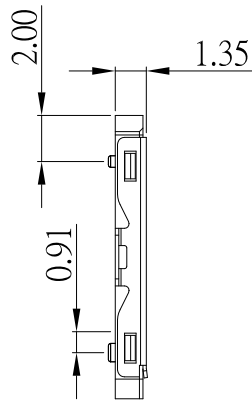
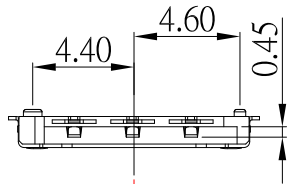


SIM pin assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



PCB通空位置

RECOMMENDED PCB LAYOUT

P.C.B LAYOUT MOUNTING PATTERN

MATERIALS:

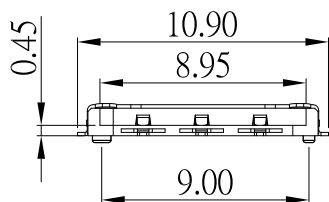
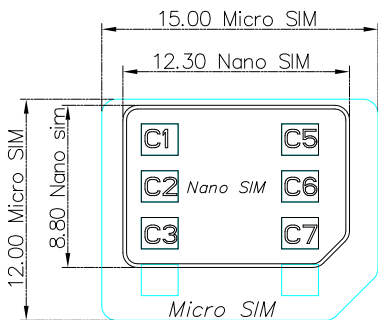
1. HOUSING : HIGH TEMPERATURE THERMOPLASTIC
2. CONTACT : PHOSPHOR BRONZE
3. SHELL : SUS

Finish:

1. Finish: CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
2. SHELL: NICKEL UNDER PLATED SURFACE LAYER

SPECIFICATION:

1. CURRENT RATING : 0.5 mA AC / DC MAX.
2. VOLTAGE RATING : 125V AC / DC
3. INSULATION RESISTANCE : 1000MΩ MIN.
4. CONTACT RESISTANCE : 100mΩ MAX.
5. OPERATING TEMPERATURE RANGE : -40°C TO +85°C.
6. STORAGE TEMPERATURE RANGE : -40°C TO +85°C.



CONTACT

建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED:
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 02/01/23
DATE: 02/01/23
DATE: 02/01/23

MAT'L
FINISH
SCALE
SHEET NO.

TITLE
MODLE
DWG NO.
PART NO.

CONNECTOR
Nano SIM CARD NO PUSH 1.35H 有柱
NSIM-0201G06A-S267
NSIM-0201G06A-S267

SIZE
A4
VER
R2